

# GCSP-10LD

## Low Density Silicone Thermal Interface Pad

### Features

- Low density, ideal for weight limited applications
- 1.0 W/m K thermal conductivity
- With single side adhesive
- Long term stability
- >10 kV breakdown voltage
- ROHS/REACH compliant



### Typical Applications

- Electric vehicle battery cooling
- Portable electronic devices
- RF circuits

### Configurations

| Part number           | Total thickness |
|-----------------------|-----------------|
| GCSP-10LD-150x150-0.5 | 0.5mm           |
| GCSP-10LD-150x150-3.0 | 3.0mm           |
| GCSP-10LD-150x150-5.0 | 5.0mm           |

### Properties

| Characteristic   | Test Method | Value             |
|--|-------------|-------------------|
| Colour   | Visual      | Pink/Yellow       |
| Available thickness range (mm)                         | ASTM D374   | 0.3~5.0           |
| Reinforcement Layer                                    | -           | Fibreglass        |
| Thermal conductivity W/mK                              | ASTM D5470  | 1.0               |
| Thermal impedance (°C-in <sup>2</sup> /W) @1.0mm 20PSI | ASTM D5470  | 1.03              |
| Thermal impedance (°C-in <sup>2</sup> /W) @1.0mm 50PSI | ASTM D5470  | 0.83              |
| Density g/cm <sup>3</sup>                              | ASTM D792   | 1.6               |
| Hardness (Shore 00)                                    | ASTM D2240  | 50                |
| Dielectric breakdown strength, kV/mm                   | ASTM D149   | >10.0             |
| Tensile strength (PSI)                                 | ASTM D149   | >300              |
| Operational temperature °C                             | EN344       | -60 ~ +150        |
| Volume resistivity (Ωcm)                               | ASTM D257   | >10 <sup>11</sup> |
| Flammability   | UL94        | V-0               |

